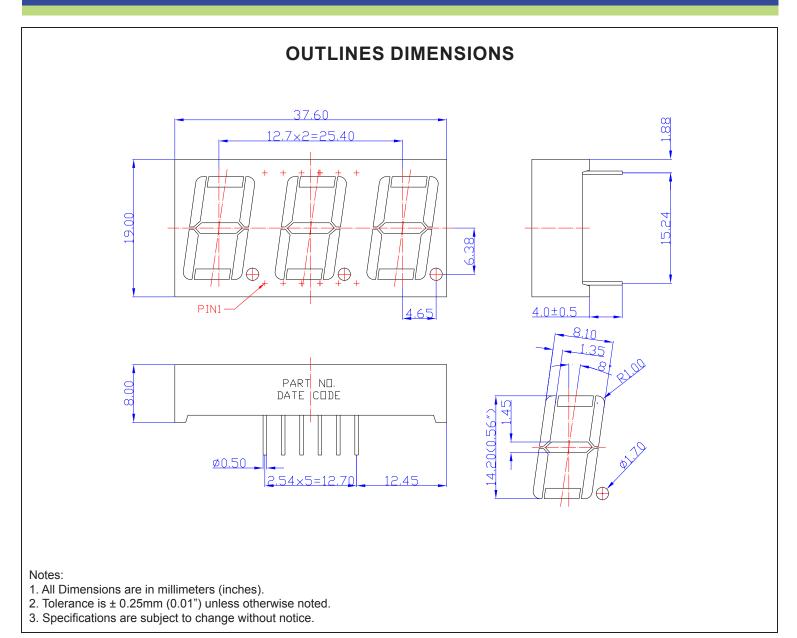


SPECIFICATIONS CDTA56R2W

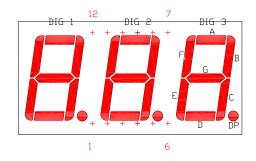


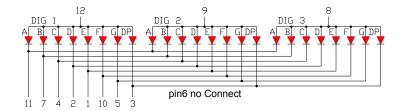
Part Number	Chip Material	Color of Emission Lens Type		Description	
CDTA56R2W	InGaAlP	Red	White Segment	Common Anode	





TYPICAL INTERNAL EQUIVALENT CIRCUIT









ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit			
Power Dissipation	Pb	70	mW			
Pulse Forward Current	lFP	90	mA			
Continuous Forward Current	lF	25	mA			
Reverse Voltage Segment	VR	5	V			
Operating Temperature Range	Topr	-25~+85	°C			
Storage Temperature Range	Тѕтс	-25~+85	°C			
IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec						

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

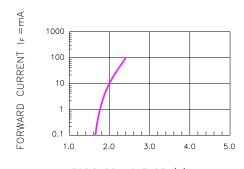
Deremeter	Symbol	Toot Condition	Value			Lloit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	I _F = 20mA	-	30	-	mcd
Forward Voltage	VF	I _F = 20mA	1	2.0	2.6	V
Reverse Leakage Current	lR	V _R = 5V	-	-	10	μΑ
Peak Wavelength	λР	I⊧ = 20mA	-	632	-	nm
Dominant Wavelength	λD	I⊧ = 20mA	619	624	629	nm
Spectral Radiation Bandwidth	Δλ	I⊧ = 20mA	-	20	-	nm



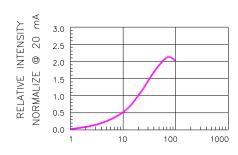


OPTICAL CHARACTERISTIC CURVES

(25 °C Free Air Temperature Unless Otherwise Specified)



FORWARD VOLTAGE (V)
Fig.1 FORWARD CURRENT VS. FORWARD VOLTAGE



FORWARD CURRENT (mA)
Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT

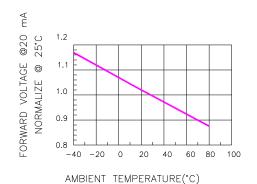


Fig.3 FORWARD VOLTAGE VS. TEMPERATURE

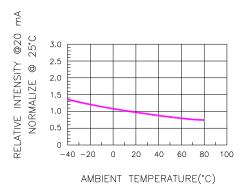


Fig.4 RELATIVE INTENSITY VS. TEMPERATURE

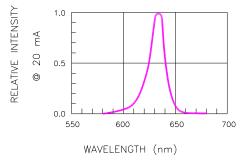
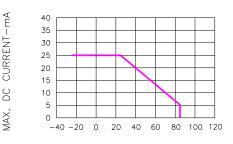


Fig.5 RELATIVE INTENSITY VS. WAVELENGTH



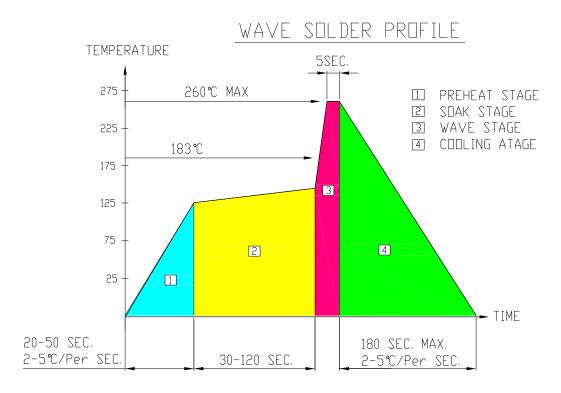
AMBIENT TEMPERATURE (TA)-°C Fig.6 MAX. ALLOWABLE DC CURRENT VS. AMBIENT TEMPERATURE





SOLDERING CONDITIONS - DISPLAY TYPE LED

RECOMMEND SOLDERING PROFILE



Note:

- Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- Peak wave soldering temperature between 245°C ~ 225°C for 3 sec (5 sec max)
- No more than one wave soldering pass

SOLDERING IRON

Basic spec is ≦4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

REWORK

Customer must finish rework within ≦3 sec under 350°C. The head of soldering iron cannot touch copper foil.

